1206 SMD Chip LED - Red multicomp PRO



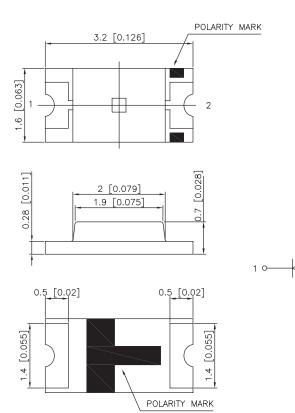
Features

- 3.2mm × 1.6mm SMT LED, 0.7mm Thickness.
- Wide Viewing Angle.
- Ideal for Backlight and Indicator.
- Various Colours and Lens Types Available

Applications

- Automotive: Backlighting in dashboard and switch.
- Telecommunication: Indicator and Backlighting in telephone and fax.
- Flat Backlight for LCD switch and symbol.

Package Dimensions



Dimensions : Millimetres

-0 2

RoHS

Compliant

Notes

1. All dimensions are in millimeters.

2. Tolerance is ±0.25 unless otherwise noted.

3. Specifications are subject to change without notice.

Device Selection Guide

Part No.	Chip		Lens Colour
MP007092	Material	Emitted Colour	Water Clear
	(InGaAIP)	Red	Water Clear

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09/03/21 V1.0

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	PD	62	mW	
Forward Current	lf	25	mA	
Peak Forward Current*1	IFP	100	mA	
Reverse Voltage	VR	5	V	
Operating Temperature	Topr	-40°C To +85°C		
Storage Temperature	Tstg	-40°C To +85°C		

Notes:

*1: Pulse width≤0.1ms, Duty cycle≤1/10

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min.	Тур.	Max	Unit	Test Conditions
Forward Voltage	VF	1.8	—	2.6	V	IF=20mA
Reverse Current	lr	—	_	10	μA	VR=5V
Dominate Wavelength	λd	617	_	629	nm	IF=20mA
Luminous Intensity	lv	500	—	845	mcd	IF=20mA
Viewing Angle	201/2	—	120	—	Deg.	IF=20mA

Remarks:

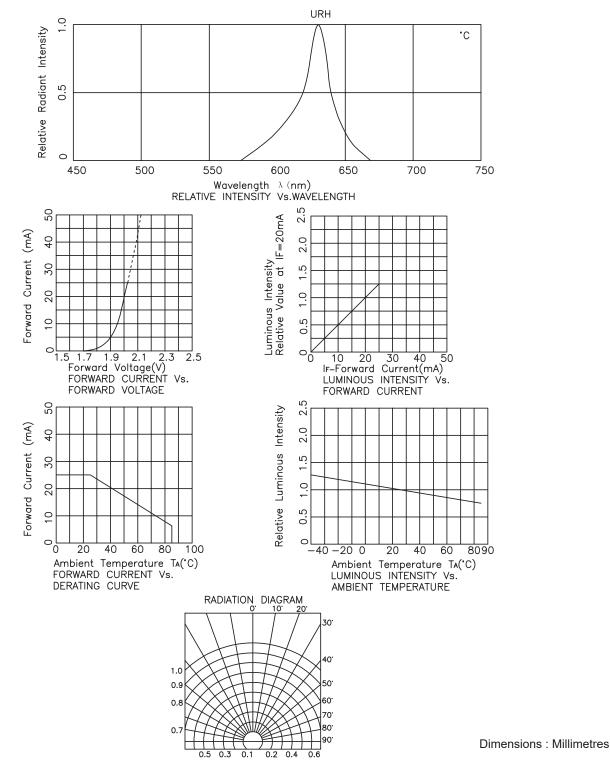
If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or chromaticity), the typical accuracy of the sorting process is as follows:

1. wavelength: ±1nm

2. Luminous Intensity: ±15%

3. Forward Voltage: ±0.1V





Typical Electrical/Optical Characteristics Curves

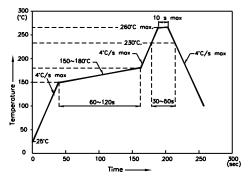
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Soldering Profile

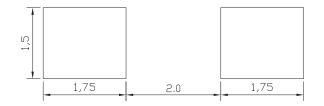
Reflow Soldering Profile For Lead-free SMT Process.



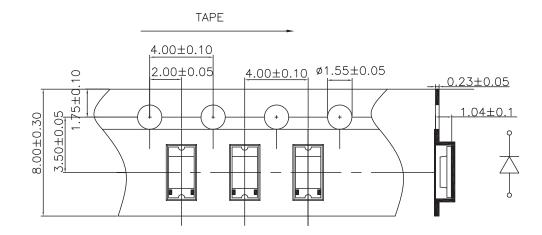
Notes

- 1. We recommend the reflow temperature 245°C. (±5°C) The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended soldering pattern



Tape specifications



Dimensions : Millimetres

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Storage

- Storage condition before opening the package: 5°C to 30°C, the largest percentage relative humidity is 60% and the storage period is one month. The LEDs beyond the storage period just can be used after dealing as step 4.
- After opening the package, If the LEDs will be Infrared reflow soldering, Oxygen phase reflow soldering or any other welding.
 - a. must be welding within 24 hours.
 - b. the storage humidity must be below 30% .
- If the situation does not satisfy 2a or 2b, the LEDs must be roasted.
- If the LEDs need to be roasted, the roast temperature should be 60°C+/-3 and the roast timeshould be 48 hours.

ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

The following procedures may decrease the possibility of ESD damage.

- · All production machinery and test instruments must be electrically grounded.
- Use a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- Maintain a humidity level of 50% or higher in production areas.
- · Use anti-static packaging for transport and storage.

Cleaning

- Led should be cleaned in a normal temperature and the time for cleaning should be less than 3 minutes; please use Alcohol as cleaner ,before you use other cleaning solvent ,please make sure that the cleaner will not make any damage to the LED performance or the appearance .
- Ultrasonic Cleaning is also commonly used for cleaning LED, please verify the Ultrasonic cleaning's Power and time to avoid any damage to the LED.

Part Number Table

Description	Part Number	
Chip LED, Red, 120°, 845mcd, 1206	MP007092	

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